

XS5801-SIP of Power Bank Total Solution

GENERAL DESCRIPTION

XS5801 is one SIP that it integrates Li-Battery Charge management、Li-Battery Protection and Boost converter in only SOP8-PP package.

This SIP can charge with 1A current and also can output 5V 1A to load such as smart phone or MID.

It only need few components and can reduce the BOM area and BOM cost.

FEATURES

- Charger input voltage-4.5V to 6V
- Charger current-MAX 1A
- Boost converter-MAX 14V output
- Boost converter-MAX 5V 1A
- Boost converter Frequency-1.2MHz
- Li Protection OCU-4.25V ODU-2.9V
- Li Protection OCP-3A
- Have UVLO、OTP、Short protection
- 8-Pin SOP-PP Package

APPLICATIONS

- Power bank for MID、PAD
- Power bank for Smart Phone

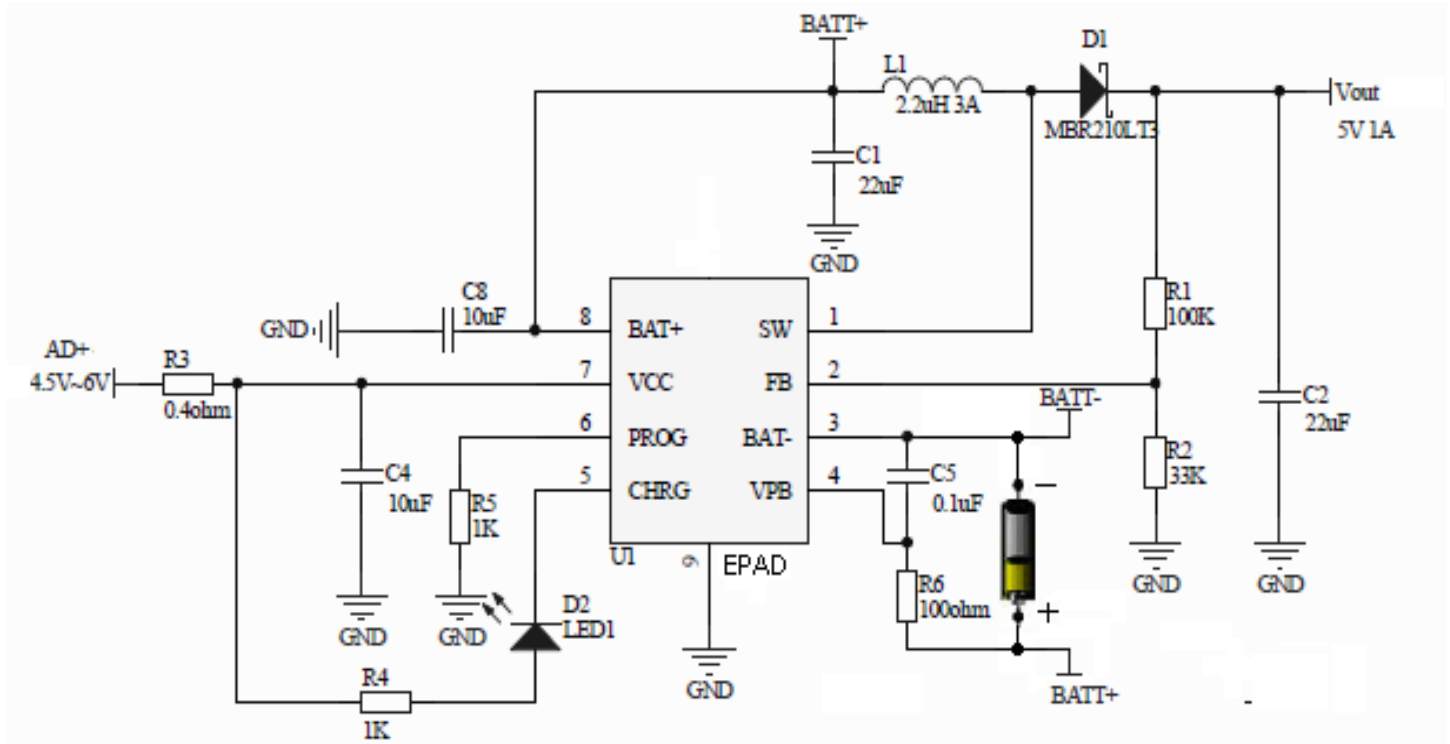


Figure 1. Typical Application Circuit1

ORDERING INFORMATION

PART NUMBER	TEMP RANGE	VIN	OUTPUT VOLTAGE (V)	CHARGE CURRENT	PACKAGE	PINS
XS5801	-40°C to 85°C	4.5~6V	ADJ	1A	SOP-PP	8

PIN CONFIGURATION

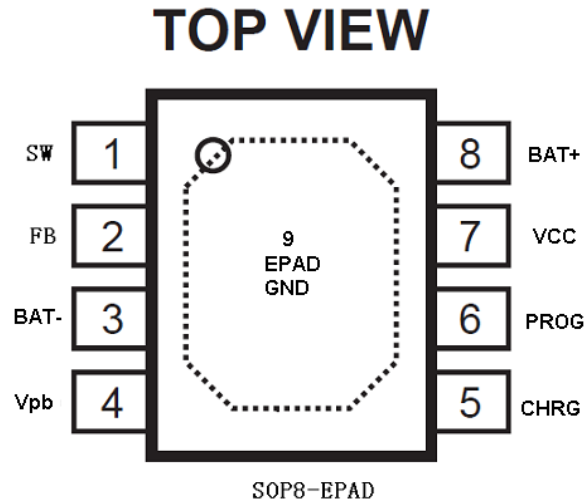


Figure 2. PIN Configuration

PIN DESCRIPTION

PIN NUMBER	PIN NAME	PIN DESCRIPTION
1	SW	Boost Converter's Switching pin
2	FB	Boost Converter's Feedback pin. it can set 5Vout with two resistors.
3	BAT-	Li-Battery's Negative Pole
4	Vpb	The Power Supply of Li-Protection section, Should connect 0.1uF capacitor between Vpb and BAT- as close as possible and 100ohm resistor to BAT+
5	CHRG	Open-Drain Charge Status Output, When the battery is charging, the CHRG pin is pulled low by an internal N-channel MOSFET. When the charge cycle is completed, CHRG pin will be in a high-impedance state.
6	PROG	Charge Current Program, Charge Current Monitor and Shutdown Pin.
7	VCC	Positive Input Supply Voltage, should be bypassed with at least a 10uF capacitor.
8	BAT+	Li-Battery's Positive Pole, should be bypassed with at least a 22uF capacitor.
9	GND	Ground and EPAD

ABSOLUTE MAXIMUM RATINGS

(Note: Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.)

PARAMETER	VALUE	UNIT
Supply Voltage VIN; CHRG Voltage	-0.3 to 7	V
FB Voltage; Vpb Voltage; BAT+; BAT-	-0.3 to 5	V
SW Voltage	Vin+0.3 to 15	V
PROG Voltage	-0.3~Vcc+0.3	V
Icharge	1.2	A
PROG Pin current	1.2	mA
Operating Ambient Temperature	-40 to 85	°C
Maximum Junction Temperature	150	°C
Storage Temperature	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	260	°C

ELECTRICAL CHARACTERISTICS

(VIN = 3.6V, TA= 25°C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input Voltage Range	VCC		4.5		6.0	V
Regulated Charge Voltage	Vfloat	0°C ≤ TA ≤ 85°C, Icharge = 40mA	4.158	4.2	4.242	V
PROG pin Voltage	Vprog	R _{PROG} = 1k, Current mode	0.93	1.0	1.07	V
Charge current	Icharge	R _{PROG} = 2k, Current mode	450	500	550	mA
		R _{PROG} = 1k, Current mode	900	1000	1100	mA
		Standby mode, Vbat=4.2V	0	-2.5	-6	uA
Trickle charge current	Itrikl	Vbat < Vtrikl, Rprog=1k	90	100	110	mA
Trickle charge Threshold Voltage	Vtrikl	R _{PROG} = 10K, Vbat Rising	2.8	2.9	3.0	V
Trickle voltage hysteresis voltage	Vtrhys	R _{PROG} = 10K	60	80	110	mV
CHRG pin Output low voltage	Vchrg	Ichrg=5mA		0.35	0.6	V
Recharge Battery threshold Voltage	Δ Vrecg	V _{FLOAT} - V _{RECHRG}		100	200	mV
Overcharge Detection Voltage of Li BAT-Protection	V _{CU}		4.225	4.25	4.275	V
Overcharge Release Voltage of Li BAT-Protection	V _{CL}		4.075	4.10	4.125	V

Overdischarge Detection Voltage of Li BAT-Protection	V _{DL}		2.85	2.9	2.95	V
Overdischarge Release Voltage of Li BAT-Protection	V _{DR}		2.95	3.0	3.05	V
Overdischarge Current1 Detection of Li BAT-Protection	I _{IOV1}	(V _{BAT+})-(V _{BAT-})=3.5V	2.1	3	3.9	A
Load Short-Circuiting Detection of Li BAT-Protection	I _{SHORT}	(V _{BAT+})-(V _{BAT-})=3.5V	10	20	30	A
Boost output voltage range	V _{out}		14			V
Regulated Feedback Voltage	V _{FB}		1.21	1.24	1.27	V
Peak Inductor Current	I _{PEAK}			4.0		A
Boost Convert Oscillator Frequency	F _{OSC}		0.9	1.2	1.5	MHz

FUNCTIONAL DESCRIPTION

NORMAL OPERATION

XS5801 integrates Li-Battery Charger 、Li-Battery Protection and Boost converter in only SOP8-PP package

Adapter inputs 5V voltage and charges the battery. After the battery is full, get off the adapter . And then we can boost up to 5V to charge the mobile advices when they is empty.

Li-Battery Charger can set charge current by PROG resistor. Normal charging current is set from 0.5A to 1A. It will go into trickle charge mode to protect Li-Battery when BAT voltage is below 2.9V.

Li-Battery Protection can detect the battery cell's status such as V_{cu}、V_{cl}、Temp、short-cut、Over-current and take action to protect battery cell.

Boost section can give us 5V 1A capacity to mobile devices.

THERMAL OR SHORT-CUT PROTECTION

A thermal shutdown is implemented to prevent damages due to excessive heat and power dissipation. Typically the thermal shutdown threshold is 150℃ .When the thermal shutdown is triggered the device stops switching until the temperature falls below typically 136℃ .Then the device starts switching again.

If the Boost converter's V_{out} is short to GND, the IC will shut down and you should recharge the battery to get rid of this status.

APPLICATION INFORMATION

INDUCTOR SELECTION

In normal operation, the inductor maintains continuous current to the output. The inductor current has a ripple that is dependent on the inductance value. The high inductance reduces the ripple current.

Selected inductor by actual application:

Manufacturer	Part Number	Inductance (uH)	DRC max (Ohms)	Dimensions L*W*H(mm3)
Murata	LQH44PN	2.2	0.049	4*4*1.7
		3.3	0.065	
		4.7	0.08	
		10	0.16	
	LQH5BP	2.2	0.030	5*5*2
		3.3	0.044	
		4.7	0.058	
		10	0.106	
TDK	SPM6530T	2.2	0.017	7.1*6.5*3
		3.3	0.027	
		4.7	0.036	
WURTH	744373	2.2	0.061	4.4*4.05
	24022			
	744777004	4.7	0.025	7.3*7.3*4.5

Table 1. Recommend Surface Mount Inductors

If output voltage is 5V , you can use 2.2uH~ 4.7uH, If output voltage is 12V, 4.7uH~ 10uH is OK,

Normal application: Input 3.3V (3.6V or 4.2V) to Output 5V 9V 12V ;
 Input 5V to Output 9V 12V

CAPACITOR SELECTION

The input capacitor reduces input voltage ripple to the converter, low ESR ceramic capacitor is highly recommended. For power bank application, A 10uF ceramic capacitor is used. The input capacitor should be placed as close as possible to VCC and GND. Such as Murata GRM21BR60J106 or TDK C3216X5R1A106M

A low ESR output capacitor is required in order to maintain low output voltage ripple. one 22uF ceramic output capacitor is suitable for most applications. Such as GRM21BR60J226 or TDK C3216X5R1A226M

Between BAT+ and GND one 22uF ceramic capacitor is needed. If this capacitor is far from BAT+ pin, you should add another 10uF ceramic capacitor between BAT+ pin and GND as close as possible.

SET CHARGE CURRENT

The charge current is programmed by connecting a 1% resistor, R_{PROG}, PROG pin to ground. When charging in constant-current mode, this pin serves to 1V. In all modes, the voltage on this pin can be used to measure the charge current using the following formula:

$$I_{\text{charge}} = (V_{\text{PROG}}/R_{\text{PROG}}) \cdot 1000.$$

OUTPUT VOLTAGE PROGRAMMING

The output voltage is set by a resistive divider according to the following equation:

$$R_1 = R_2 \times \left(\frac{V_{OUT}}{1.24} - 1 \right)$$

Typically choose R2=33K and determine R1 from the following equation:

For example, you can select R2=33K R1=100K to set 5Vout

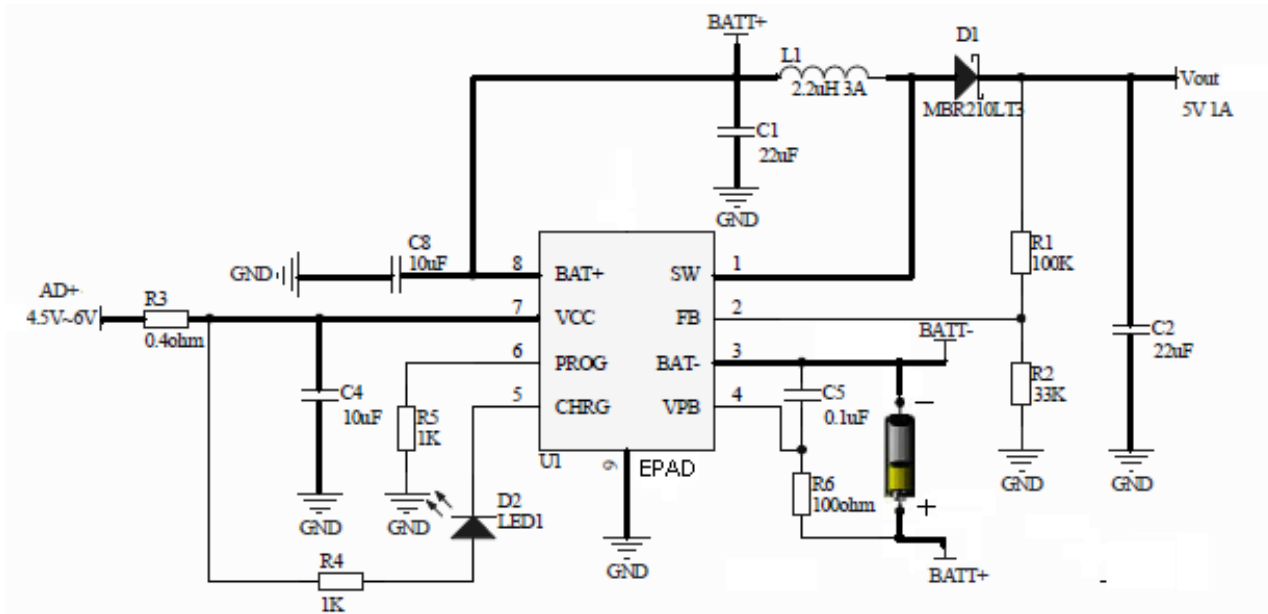
DIODE SELECTION

According to max Iout and max Vout, you can select suitable diode. Normally we select diode $I_f = (1.5 \sim 2) \times I_{outmax}$ and $V_R = (1.5 \sim 2) \times V_{outmax}$. For high efficiency, suggest that you select low Vf Schottky diode.

For example, 5V 1Aout power bank application, you can select MBR210LT3 or SS24. Using MBR210LT3, you can get higher efficiency.

PCB LAYOUT GUIDE

- 1) It is desirable to maximize the PCB copper area connecting to GND pin to achieve the best thermal and noise performance. If the board space allowed, a ground plane is highly desirable
- 2) C_{IN} must be close to Pins VCC and GND. The loop area formed by C_{IN} and GND must be minimized. C_{BAT} is the same
- 3) The PCB copper area associated with SW pin must be minimized to avoid the potential noise problem.
- 4) The components R1 and R2, and the trace connecting to the FB pin must NOT be adjacent to the SW net on the PCB layout to avoid the noise problem
- 5) Please make sure that the big current circuits are board and short to reduce the circuit Rdson is minimum.

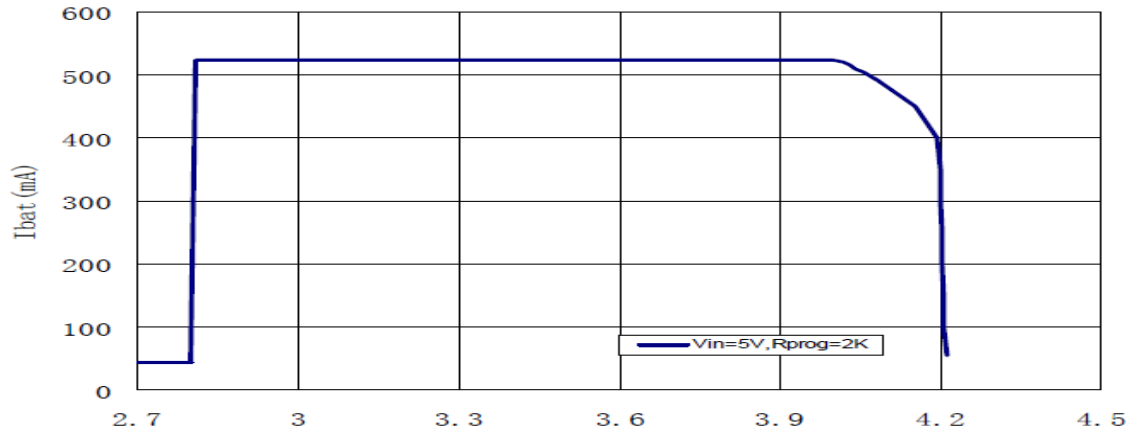


BIG CURRENT CIRCUIT

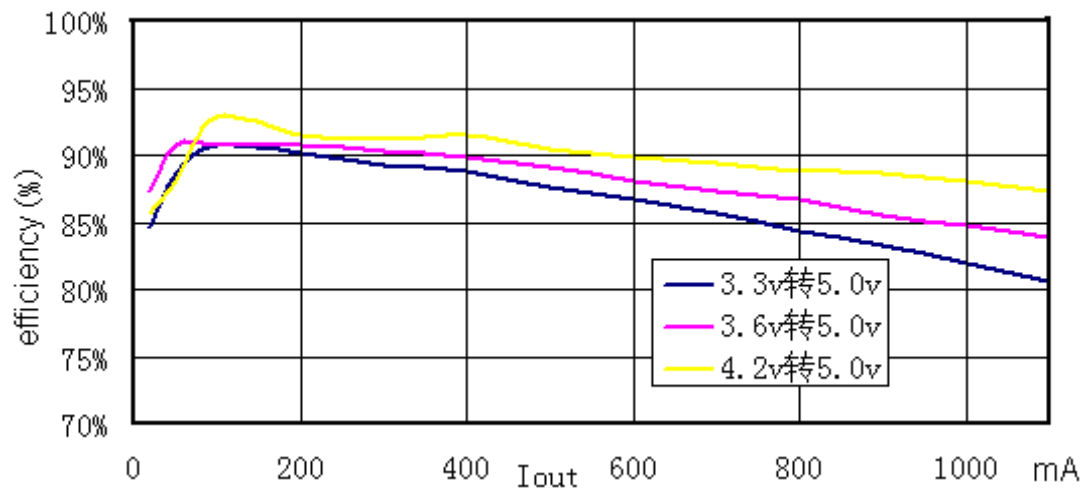
As above(Heavy Lines)

TYPICAL PERFORMANCE CHARACTERISTICS

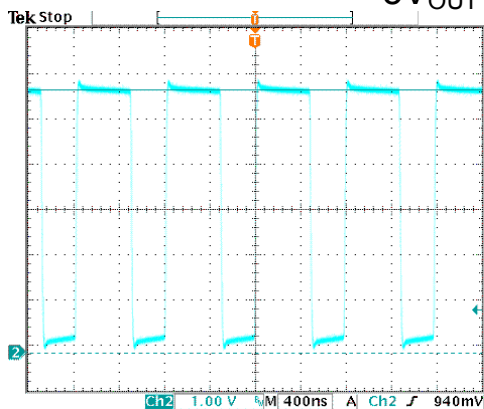
(L=2.2uH-SPM6530T2R2, C_{IN}=10uF, C_{BAT+}=22uF, C_{out}=22uF, D=MBRA210LT3 Vin=5V if not mentioned)



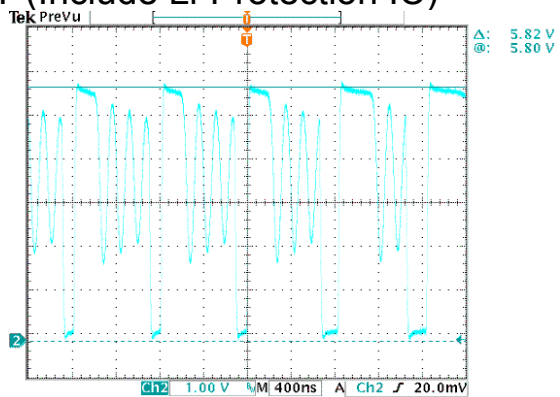
BATTERY CHARGER CURVE



5V_{OUT} EFFICIENCY (Include Li-Protection IC)



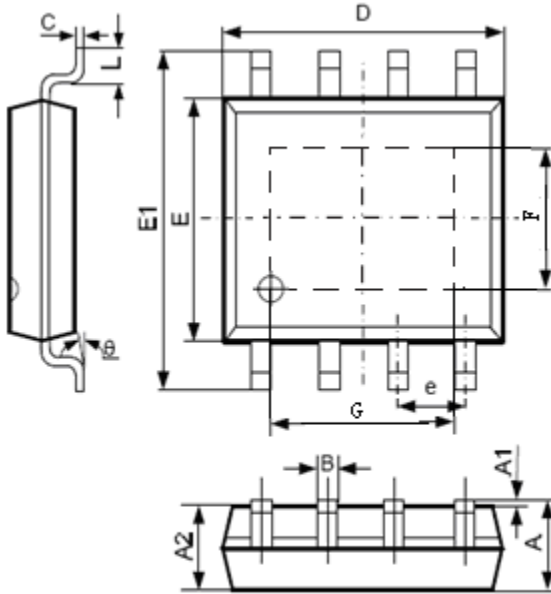
PWM SWITCHING CONTINUOUS CONDUCTION MODE



PWM SWITCHING DISCONTINUOUS CONDUCTION MODE

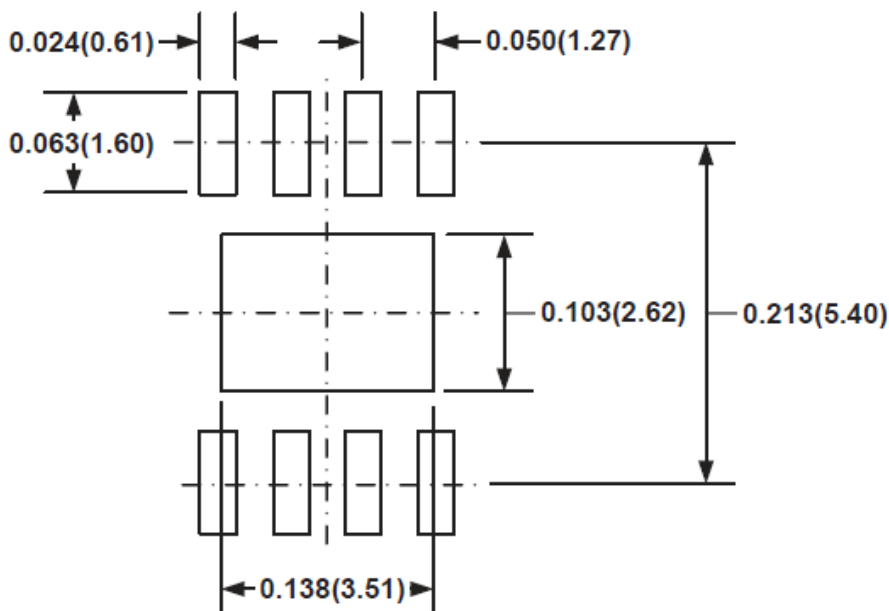
PACKAGE OUTLINE

SOP8-PP PACKAGE OUTLINE AND DIMENSIONS



SYMBOL	Dimension in Millimeters		Dimension in Inches	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
B	0.330	0.510	0.013	0.020
C	0.190	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
E	3.800	4.000	0.150	0.157
E1	5.800	6.300	0.228	0.248
e	1.27 TYP		0.050 TYP	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°
F	2.26	2.56	0.089	0.101
G	3.15	3.45	0.124	0.136

In order to increase the driver current capability of XS5801 and improve the temperature of package, Please ensure Epad and enough ground PCB to release energy.



PROUCT CHANGE NOTICE LIST

NO	Updated date	Version update	Update content
1	2013-3-21	Rev 0.1	Create datasheet
2	2013-3-26	Rev0.2	Add big current circuits
3	2013-10-21	Rev0.3	S5801 transfer to XS5801